



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Wilkins  
Title : Die-First Multi-Chip Modules And Methods Of Manufacture  
Application No. : 10/724,981  
Filed : November 30, 2003  
Attorney Docket No. : 783403605015

I hereby certify that this correspondence is being deposited today with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

on September 21, 2006

By: Kathie G. Kopylov

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**STATUS INQUIRY**

Dear Sir:

The above-referenced application was filed in the United States on November 30, 2003, and we have not yet received an Office Action or Notice of Allowance for the same. Please advise the undersigned when we should expect to receive an action or notice.

Respectfully submitted,

David B. Cochran

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Date: 9/21/06